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CONTENTS

September 2009

| PAGE | REGULAR ISSUE PAPERS |
|------|---|
| 1815 | Dynamic Recrystallization (DRX) as the Mechanism for Sn Whisker Development. Part I: A Model P.T. Vianco and J.A. Rejent |
| 1826 | Dynamic Recrystallization (DRX) as the Mechanism for Sn Whisker Development. Part II: Experimental Study P.T. Vianco and J.A. Rejent |
| 1838 | Spreading Kinetics of Liquid Solders over an Intermetallic Solid Surface. Part 1: Eutectic Lead Solder H. Zhao, H.Q. Wang, D.P. Sekulic, and Y.Y. Qian |
| 1846 | Spreading Kinetics of Liquid Solders over an Intermetallic Solid Surface. Part 2: Lead-Free Solders H. Zhao, H.Q. Wang, D.P. Sekulic, and Y.Y. Qian |
| 1855 | Constitutive Relations of Indium in Extreme-Temperature Electronic Packaging Based on Anand Model Rui Wu Chang and F. Patrick McCluskey |
| 1860 | Intermetallic Reaction of Indium and Silver in an Electroplating Process Pin J. Wang, Jong S. Kim, and Chin C. Lee |
| 1866 | Constitutive Relations for Creep in a SnCu-Based Composite Solder Reinforced with Ag Particles Yaowu Shi, Yanfu Yan, Jianping Liu, Zhidong Xia, Yongping Lei, Fu Guo, and Xiaoyan Li |
| 1874 | Monitoring the Growth of the α Phase in Tin Alloys by Electrical Resistance Measurements D. Di Maio and C.P. Hunt |
| 1881 | A Novel Mechanism of Embrittlement Affecting the Impact Reliability of Tin-Based Lead-Free Solder Joints Konstantina Lambrinou, Wout Maurissen, Paresh Limaye, Bart Vandevelde, Bert Verlinden, and Ingrid De Wolf |
| 1896 | Fracture Mechanics of Solder Bumps During Ball Shear Testing: Effect of Bump Size Woong Ho Bang, Choong-Un Kim, Suk Hoon Kang, and Kyu Hwan Oh |
| 1906 | Study of Solidification Cracks in Sn-Ag-Cu Lead-Free Solder Joints Wenxing Dong, Yaowu Shi, Yongping Lei, Zhidong Xia, and Fu Guo |
| 1913 | Rutherford Backscattering Spectrometry Analysis of Self-Formed Ti-Rich Interface Layer Growth in Cu(Ti)/Low-h Samples Kazuyuki Kohama, Kazuhiro Ito, Kenichi Mori, Kazuyoshi Maekawa, Yasuharu Shirai, and Masanori Murakami |
| 1921 | Low Fatigue in Epitaxial Pb(Zr _{0.2} Ti _{0.8})O ₃ on Si Substrates with LaNiO ₃ Electrodes by RF Sputtering Chun Wang and Mark H. Kryder |
| 1926 | Amorphization and Solid-Phase Epitaxial Growth of C-Cluster Ion-Implanted Si N.G. Rudawski, L.R. Whidden, V. Craciun, and K.S. Jones |
| 1931 | How r-Plane Al ₂ O ₃ Surface Modifications Impact the Growth of Epitaxial (001) CeO ₂ Thin Films Madhana Sunder and P.D. Moran |
| 1938 | Comparative Study on MOCVD Growth of a-Plane GaN Films on r-Plane Sapphire Substrates Using GaN, AlGaN, and AlN Buffer Layers |
| 1944 | J.N. Dai, Z.H. Wu, C.H. Yu, Q. Zhang, Y.Q. Sun, Y.K. Xiong, X.Y. Han, L.Z. Tong, Q.H. He, F.A. Ponce, and C.Q. Chen Electrical Characterization of Different Passivation Treatments for Long-Wave Infrared InAs/GaSb Strained Layer Superlattice Photodiodes Koushik Banerjee, Siddhartha Ghosh, Shubhrangshu Mallick, Elena Plis, and Sanjay Krishna |

| 1948 | Interband Cascade Lasers with Wavelengths Spanning 3.2–4.2 µm C.L. Canedy, J.R. Lindle, W.W. Bewley, C.S. Kim, M. Kim, J.A. Nolde, I. Vurgaftman, and J.R. Meyer |
|------|--|
| 1952 | Edge-Emitting Lead Salt Mid-Infrared Laser Structure on BaF ₂ (110) Substrate D. Li, S. Mukherjee, J. Ma, G. Bi, D. Ray, F. Zhao, S.L. Elizondo, G. Yu, and Z. Shi |
| 1956 | p-Type PbTe Thermoelectric Bulk Materials with Nanograins Fabricated by Attrition Milling and Spark Plasma Sintering Chia-Hung Kuo, Ming-Shan Jeng, Jie-Ren Ku, Shih-Kuo Wu, Ya-Wen Chou, and Chii-Shyang Hwang |
| 1962 | Characterization of $Zn_{1-x}Mg_xO$ Films Prepared by the Sol–Gel Process and Their Application for Thin-Film Transistors Chien-Yie Tsay, Min-Chi Wang, and Shin-Chuan Chiang |
| 1969 | Preparation and Characterization of Ultrasonically Sprayed Zinc Oxide Thin Films Doped with Lithium Vildan Bilgin |
| 1979 | Silicon Nitride Films Deposited by RF Sputtering for Microstructure Fabrication in MEMS Vivekanand Bhatt and Sudhir Chandra |
| 1990 | Two Layer Surface Exfoliation on Si ₃ N ₄ /Si by Sequential Implantation of He and H Ions Mengkai Li, Zhuo Wang, Changlong Liu, Junqi Liao, Yanyan Shen, Lili Zhang, and Bing Yuan |
| 1995 | Electrical Properties of Organic-Inorganic Semiconductor Device Based on Rhodamine-101 M. Çakar, Ö. Güllü, N. Yildirim, and A. Türüt |
| 2000 | Synthesis and Characterization of Naphthalene End-Capped Divinylbenzene for OTFT Sung Jin Park, Sul Ong Kim, Sung Ouk Jung, Mi-Hye Yi, Yun-Hi Kim, and Soon-Ki Kwon |
| 2006 | Femtosecond Laser Drilling of Alumina Wafers Chengde Li, Seongkuk Lee, and Suwas Nikumb |
| 2013 | Electrical Properties of Isotropic Conductive Adhesives Composed of Silicone-Based Elastomer Binders Containing Ag Particles Masahiro Inoue, Hiroaki Muta, Shinsuke Yamanaka, and Katsuaki Suganuma |